

UPB409A - PRELIMINARY

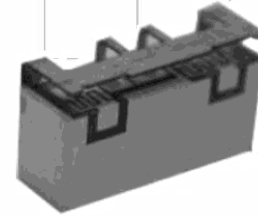
3980-4200MHz UPB Series TDD Bandpass Filter

Features

- Low Loss with High Rejection
- Low ripple
- Universal footprint across family for all TDD bands

Applications

- Wireless Infrastructure applications
- High-performance carrier-grade single-band TDD Pico-cell basestations for 0.25-0.5W at the antenna port.



Part Dimensions: 10.2 x 5.1 x 4.0 mm • < 1 g
Materials: Ag plated ceramic block with tin plated brass shield

Description

Surface mount ceramic bandpass filter supports a universal footprint across all TDD frequency bands enabling the use of a common system PCB. Superior rejection, insertion loss, reliability, as well as both peak and average power handling compared other bandpass filter technologies.

Electrical Specifications

Parameter	Frequency (MHz)	Typical at 25°C	Spec. at 25°C	Spec. over -40°C to +85°C
Nominal Impedance	-	50 ohms	-	-
Average Input Power	-	-	-	2.0 Watt max
Peak Input Power	-	-	-	20 Watt max

Input-Output Response

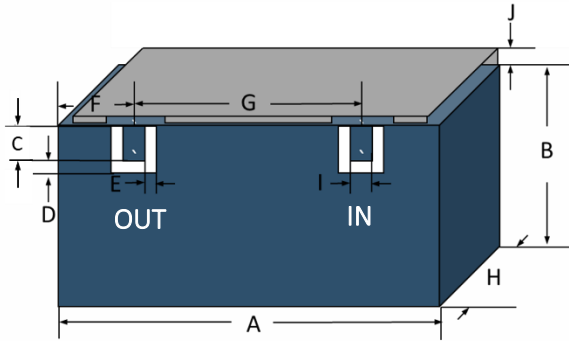
Passband Insertion Loss (20 MHz avg)	3980-4200	1.0 dB	1.2 dB max	1.2 dB max
Passband Ripple	3980-4200	0.3 dB	0.5 dB max	0.5 dB max
Passband Return Loss	3980-4200	14 dB	12 dB min	12 dB min
Attenuation:	1-3730	40 dB	30 dB min	30 dB min
	4450-5925	31 dB	30 dB min	30 dB min
	5926-7125	30 dB	20 dB min	20 dB min

Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances.

Specification Allowance

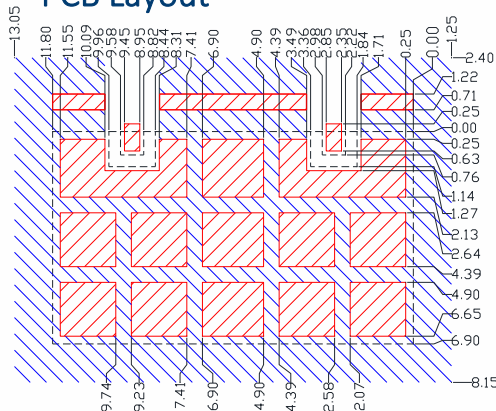
Insertion Loss	0.1 dB
Return Loss	1.0 dB
Attenuation	1.0 dB




Mechanical Drawing



Dim.	Nominal (mm)	Tolerance (±mm or Max)
A	10.20	0.13
B	3.60	0.30
C	0.76	0.13
D	0.38	0.13
E	0.38	0.13
F	1.80	0.13
G	6.60	0.13
H	3.80	0.30
I	0.76	0.13
J	0.90	0.30

PCB Layout



-----	Filter Outline		Solder Resist Over Dielectric
	Exposed Conductor		Solder Resist Over Conductor

IMPORTANT: Please assure $\geq 30\text{mils}$ (0.75mm) thickness of dielectric beneath the I/O Pads and the surrounding clearance zone down to the ground plane.

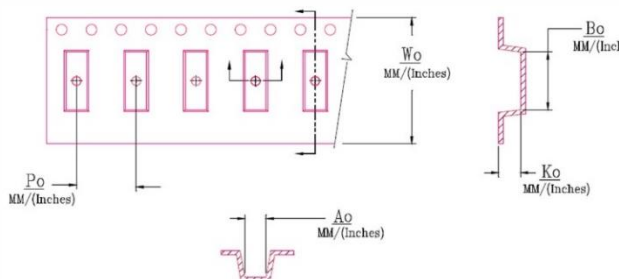
Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

Recommended solder: 4-6 mils of SAC305 with reflow including 120s of soak at 217°C, and up to 30 sec peak at 241°C.

Packaging and Marking

Dimension	Units	Spec.	Product Marking
Reel Diameter	mm	330	<div> <div>CTS</div> <div>409</div> <div>YWW</div> </div>
Reel Weight	kg	5.5	
Reel Quantity	ea.	500	

Customer Feed Direction → → →



W _o	A _o	B _o	K _o	P _o
0.945 in 24.0 mm	0.205 in 5.20 mm	0.406 in 10.30 mm	0.165 in 4.2 mm	0.472 in 12.0 mm

Electrical Response

